



## Material Content Data Sheet



Sales Product Name	ESD3V3XU1US E6327			Issued		11. May 2015		
MA#	MA001012934							
Package	PG-TSSLP-2-1			Weight*		0.15 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.000	0.23		2340	
	noble metal	gold	7440-57-5	0.001	0.91		9063	
	inorganic material	silicon	7440-21-3	0.010	6.72	7.86	67178	78581
leadframe	non noble metal	nickel	7440-02-0	0.036	24.38	24.38	243793	243793
wire	noble metal	gold	7440-57-5	0.003	1.69	1.69	16927	16927
encapsulation	inorganic material	antimonytrioxide	1309-64-4	0.000	0.03		295	
	organic material	carbon black	1333-86-4	0.001	0.58		5832	
	plastics	epoxy resin	-	0.012	7.87		78741	
	inorganic material	silicondioxide	60676-86-0	0.074	49.84	58.32	498404	583272
leadfinish	noble metal	gold	7440-57-5	0.004	2.76	2.76	27572	27572
plating	noble metal	silver	7440-22-4	0.007	4.99	4.99	49855	49855
*deviation	< 10%	Sum in total:				100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2011/65/EU (RoHS) and does not use any exemption.

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